



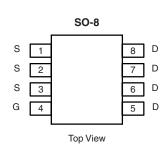
N-Channel 150-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A)		
150	0.050 at V _{GS} = 10 V	5.0		

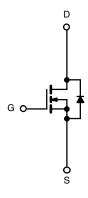
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4488DY-T1-E3 (Lead (Pb)-free) Si4488DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unles	ss otherwise n	oted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	150		V
Gate-Source Voltage		V_{GS}	± 20		V
Opation	T _A = 25 °C	- I _D	5.0	3.5	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		4.0	2.8	
Pulsed Drain Current		I _{DM}	50		Α
Avalanche Current	L = 0.1 mH	I _{AS}	25		
Continuous Source Current (Diode Conduction) ^a		I _S	2.8	1.4	
W	T _A = 25 °C	P _D	3.1	1.56	W
Maximum Power Dissipation ^a	T _A = 70 °C	r D	2.0	1.0	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55	to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manifestor Location to Australia	t ≤ 10 s	R _{thJA}	33	40	
Maximum Junction-to-Ambient ^a	Steady State	' ¹thJA	65	80	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	17	21	

a. Surface Mounted on 1" x 1" FR4 board.

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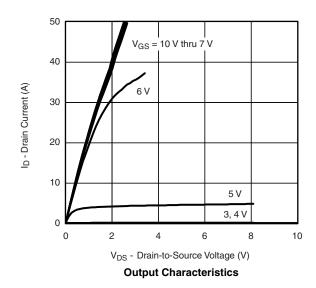


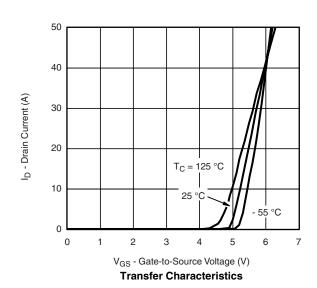
SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0			V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valtaga Drain Current	1	V _{DS} = 120 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 120 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			5	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 5 A		0.041	0.050	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 5 A		18		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 2.8 A, V _{GS} = 0 V		0.75	1.1	V	
Dynamic ^b							
Total Gate Charge	Q_g			30	36		
Gate-Source Charge	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		8.5		nC	
Gate-Drain Charge	Q_{gd}			8.5			
Gate Resistance	R_g		0.2	0.85	1.2	Ω	
Turn-On Delay Time	t _{d(on)}			12	18		
Rise Time	t _r	V_{DD} = 75 V, R_L = 15 Ω		7	11		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 10 V, R_g = 6 Ω		22	33	ns	
Fall Time	t _f			10	15		
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.8 A, dI/dt = 100 A/μs		40	70		

- Notes: a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



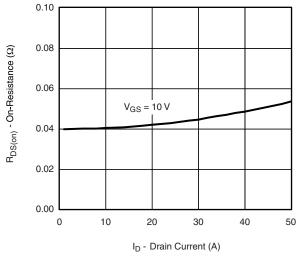




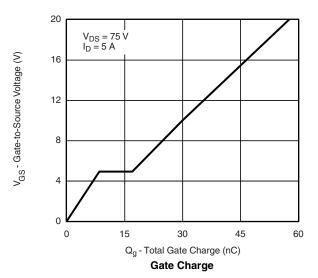




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Drain Current



T_J = 150 °C

10

T_J = 150 °C

T_J = 25 °C

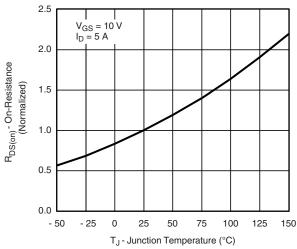
V_{SD} - Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage

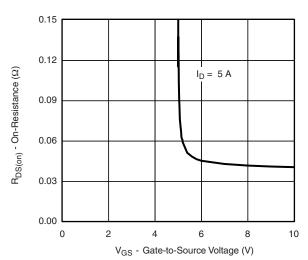
C_{rss} C_{oss} C_{iss} C_{oss}

V_{DS} - Drain-to-Source Voltage (V)





On-Resistance vs. Junction Temperature



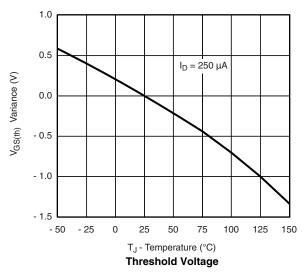
On-Resistance vs. Gate-to-Source Voltage

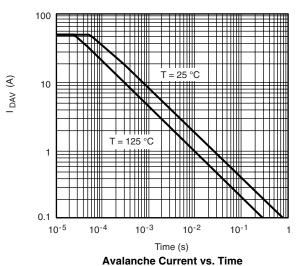
I_S - Source Current (A)

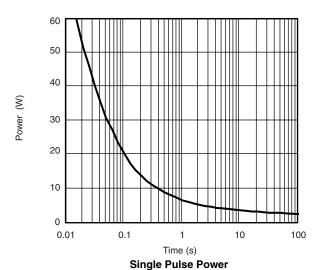
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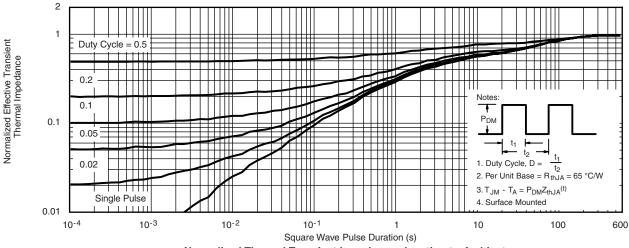
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





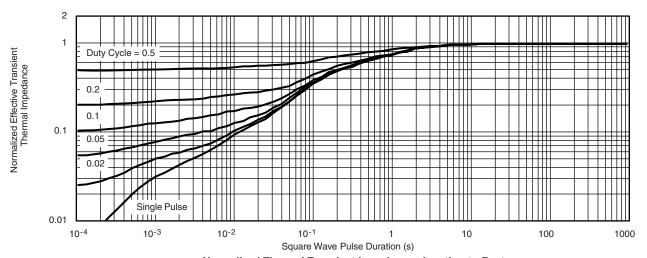




Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

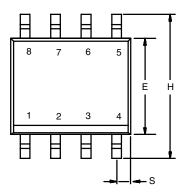


Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?71240.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Bey 11-Sen-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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